This application note gives hints and recommendations regarding correct handling and processing of sawn wafers mounted on irradiated UV dicing tape. The recommendations are based on NXP internal assembly experience and must be seen as guideline only. In addition to processing recommendations this document presents the results of various tests which have been performed by NXP in order to ensure damage-free shipment of the delivery type "sawn wafer on FFC with irradiated UV dicing tape".
Revision history

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<th>Rev</th>
<th>Date</th>
<th>Description</th>
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<tr>
<td>2.0</td>
<td>2009-01-13</td>
<td>• Section 2.3.1: recommendation regarding LASER diced wafers added</td>
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Contact information

For additional information, please visit: [http://www.nxp.com](http://www.nxp.com)

For sales office addresses, please send an email to: salesaddresses@nxp.com
1. Introduction

This application note gives hints and recommendations regarding correct handling and processing of sawn wafers mounted on irradiated UV dicing tape according the “General Specification for 8” Wafer on UV-tape”. The processing recommendations are based on NXP internal assembly experience and must be seen as guideline only. Process fine tuning and optimization remains in the full responsibility of the customer.

In addition to processing recommendations this document presents the results of various tests which have been performed by NXP in order to ensure damage- and yield loss-free shipment of the delivery type “sawn wafer on FFC with irradiated UV dicing tape”.

2. Handling and processing recommendations

2.1 Differences between irradiated UV dicing tape and conventional tape

The adhesion strength between irradiated UV dicing tape and silicon is approximately three times lower compared to non UV dicing tape (i.e. “sticky tape” or “blue tape”). Furthermore irradiated UV dicing tape almost completely loses its adhesion strength to the silicon in case excessive shear forces are applied to the adhesive layer. This leads to the following important differences for the pick and place process of sawn wafers on irradiated UV dicing tape compared to conventional blue tape:

- No or only minimum spreading of the tape is advised at the pick and place process. This prevents loose dies prior to pick and place.
- Adjustment of the mechanical pick parameters (e.g. push up needle geometry, push up forces and profile) is advised in order to reflect the lower adhesion force of the irradiated UV dicing tape properly.

2.2 General recommendations

- Optimization of the assembly process in general (equipment adaption and accurate process parameter setting) by final product manufacturer is recommended in order to prevent mechanical stress and damage of the ICs.
- Ultrasonic cleaning is not permitted.
- ESD safe working environment and equipment is advised.

2.3 Conventional assembly

2.3.1 Die Attach

- Cleaning of wafer surface by gentle N₂ blow before push up is advised.
- No or minimum spreading of sawn wafer on FFC is advised. In case of LASER diced wafers it should additionally be ensured that the working area of the pick & place equipment is made large enough to comply with the increased wafer diameter due to die separation spreading.
- Any backside damage due to improper push up needle(s), force and profile has to be avoided.
- Even distribution of adhesive under the die is advised (100% of die area should be covered with adhesive).
- Adhesive type: conductive or non-conductive.
- Adhesive thickness: min. 10 µm (standard epoxy material).

2.3.2 Wire Bonding

- Preferable process:
  - thermosonic bonding (Au wire)
- No chip out under bond pad metallization is allowed.
- No bond closer than 2 µm to the adjacent passivation layer at the edge of the bondpad.
2.4 Flip chip assembly

2.4.1 Pick and place

- Cleaning of wafer surface by gentle N₂ blow before push up is advised.
- No or minimum spreading of sawn wafer on FFC is advised.
- Any backside damage due to improper push up needle(s), force and profile has to be avoided.

2.4.2 Direct chip attach assembly (DCA)

Bumped dies offered by NXP Semiconductors can be assembled by flip chip processes using ACF (anisotropic conductive film), ACP (anisotropic conductive paste), non-conductive and conductive glues. Other compatible DCA processes are TCB (thermo compression bonding) and direct conductive paste printing.
3. Packing and shipping

3.1 Conventionally diced parts (blade dicing)

3.1.1 Shipping test program

The use of the specified packing method 3322 845 08351 for customer shipment of sawn wafers on irradiated UV dicing tape has been released based on the results of the following tests and field experience:

1. Test sequences: standard drop and vibration tests according UN-D 1400.
   a. 3 axis vibration test (frequency 7 Hz, amplitude 5.3 mm, acceleration 1.05 g, 30 min. each axis) + drop test program 1 (7 drops, 1 m drop height).
   b. 3 axis vibration test + drop test program 1 + 2 hours vibration test (most critical axis).
   c. 3 axis vibration test + drop test program 1 + 2 × 2 hours vibration test (most critical axis).

2. Shipment trial of all sample material used in item 1. from Hamburg to Bangkok and back.

3. Field experience from more than 30000 sawn wafers on irradiated UV dicing tape shipped to customers and NXP production sites.

3.1.2 Results

3.1.2.1 Standard drop and vibration tests

The results from the standard drop and vibration test sequences are shown in Table 1.

<table>
<thead>
<tr>
<th>Test sequence</th>
<th>Adwill D-175</th>
<th>Nitto UE-111AJ</th>
<th>Adwill D-175</th>
<th>Nitto UE-111AJ</th>
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</thead>
<tbody>
<tr>
<td>a.</td>
<td>5/31k</td>
<td>3/31k</td>
<td>3/62k</td>
<td>0/62k</td>
</tr>
<tr>
<td>b.</td>
<td>0/31k</td>
<td>0/31k</td>
<td>1/62k</td>
<td>0/62k</td>
</tr>
<tr>
<td>c.</td>
<td>13/31k</td>
<td>10/31k</td>
<td>24/124k</td>
<td>3/124k</td>
</tr>
</tbody>
</table>

3.1.2.2 Shipment trial with drop test material

No additional missing or delaminated dies were observed.

3.1.2.3 Field experience

To date no complaints regarding missing or delaminated dies due to shipment received.

3.2 Laser diced parts

3.2.1 Shipping test program

Test sequences: standard drop and vibration tests according UN-D 1400.

a. 3 axis vibration test (frequency 7 Hz, amplitude 5.3 mm, acceleration 1.05 g, 30 min. each axis)

b. Drop test program 1 (7 drops, 1 m drop height)
3.2.2 Results

Table 2. Missing/delaminated dies vs. total dies

<table>
<thead>
<tr>
<th>Die size: 0.3 mm²</th>
<th>Nitto UE-111AJ</th>
</tr>
</thead>
<tbody>
<tr>
<td>Wafer 1</td>
<td>Wafer 2</td>
</tr>
<tr>
<td>Test sequence a.</td>
<td>0/99k</td>
</tr>
<tr>
<td>Test sequence b.</td>
<td>0/99k</td>
</tr>
</tbody>
</table>

3.3 Conclusion

In case excessive vibration and/or dropping is applied to the packed material few dies may delaminate from the irradiated UV dicing tape. Under normal shipping conditions, however, no delamination was ever seen on more than 30000 shipped wafers. Therefore the risk for yield loss due to wafer shipping can be considered extremely low for sawn wafers on irradiated UV dicing tape.
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5. Contents

1. Introduction .........................................................3
2. Handling and processing recommendations....4
   2.1 Differences between irradiated UV dicing tape and conventional tape ................................. 4
   2.2 General recommendations .................................. 4
   2.3 Conventional assembly ...................................... 4
   2.3.1 Die Attach .................................................. 4
   2.3.2 Wire Bonding .............................................. 4
   2.4 Flip chip assembly .......................................... 5
   2.4.1 Pick and place ........................................... 5
   2.4.2 Direct chip attach assembly (DCA) .................... 5
3. Packing and shipping ......................................... 6
   3.1 Conventionally diced parts (blade dicing) .......... 6
   3.1.1 Shipping test program .................................... 6
   3.1.2 Results ..................................................... 6
   3.1.2.1 Standard drop and vibration tests ................... 6
   3.1.2.2 Shipment trial with drop test material .......... 6
   3.1.2.3 Field experience ..................................... 6
   3.2 Laser diced parts .......................................... 6
   3.2.1 Shipping test program .................................... 6
   3.2.2 Results ..................................................... 7
   3.3 Conclusion ................................................... 7
4. Legal information ................................................ 8
   4.1 Definitions .................................................. 8
   4.2 Disclaimers ................................................ 8
5. Contents ............................................................. 9